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<i>Ser Choong Chong (Institute of Microelectronics (IME), Agency for Science, Technology and Research (A*STAR), Republic of Singapore), Ling Xie (Institute of Microelectronics (IME), Agency for Science, Technology and Research (A*STAR), Republic of Singapore), Vasarla Nagendra Sekhar (Institute of Microelectronics (IME), Agency for Science, Technology and Research (A*STAR), Republic of Singapore), Mishra Dileep Kumar (Institute of Microelectronics (IME), Agency for Science, Technology and Research (A*STAR), Republic of Singapore), B.S.S. Chandra Rao (Institute of Microelectronics (IME), Agency for Science, Technology and Research (A*STAR), Republic of Singapore), and Vempati Srinivasa Rao (Institute of Microelectronics (IME), Agency for Science, Technology and Research (A*STAR), Republic of Singapore)</i>	
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Yi-Lun Hung (ASE Group, Taiwan), Yung-Sheng Lin (ASE Group, Taiwan), Min-Yan Tsai (ASE Group, Taiwan), Mingtzung Kuo (ASE Group, Taiwan), Ling-yuan Chang (ASE Group, Taiwan), Chen-Chao Wang (ASE Group, Taiwan), Ping-Feng Yang (ASE Group, Taiwan), and Chin-Pin Hung (ASE Group, Taiwan)	
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Tim Nils Bierwirth (Leibniz University Hannover, Germany), Sebastian Bengsch (Ensinger GmbH, Germany), Eike Christian Fischer (Freelancer, Germany), Michael Werner (Ensinger GmbH, Germany), and Marc Christopher Wurz (Leibniz University Hannover, Germany)	
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Soichi Homma (KIOXIA Corporation, Japan), Daichi Okada (KIOXIA Corporation, Japan), Akihito Sawanobori (KIOXIA Corporation, Japan), Susumu Yamamoto (KIOXIA Corporation, Japan), and Hiroshi Nishikawa (Osaka University, Japan)	
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Haoxiang Ren (UCLA Center for Heterogeneous Integration and Performance Scaling (UCLA CHIPS), CA), Zoe Chen (UCLA Center for Heterogeneous Integration and Performance Scaling (UCLA CHIPS), CA), Jui-Han Liu (UCLA Center for Heterogeneous Integration and Performance Scaling (UCLA CHIPS), CA), Cheng-Ting Yang (UCLA Center for Heterogeneous Integration and Performance Scaling (UCLA CHIPS), CA), Ben Yang (UCLA Center for Heterogeneous Integration and Performance Scaling (UCLA CHIPS), CA), Boris Vaisband (UCLA Center for Heterogeneous Integration and Performance Scaling (UCLA CHIPS), CA; University of California, CA), and Subramanian S. Iyer (UCLA Center for Heterogeneous Integration and Performance Scaling (UCLA CHIPS), CA)	

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<i>Akihiro Shimizu (Ushio Inc., Japan) and Shinichi Endo (Ushio Inc., Japan)</i>	
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<i>Arifur Chowdhury (Intel Corporation, USA), Jaclyn Avallone (Intel Corporation, USA), Bamidele D. Falola (Intel Corporation, USA), Taylor Gaines (Intel Corporation, USA), Haowen Liu (Intel Corporation, USA), Peng Li (Intel Corporation, USA), Sergio A Chan Arguedas (Intel Corporation, USA), and Aravindh R Antoniswamy (Intel Corporation, USA)</i>	
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